

CHA93X/CHI93X

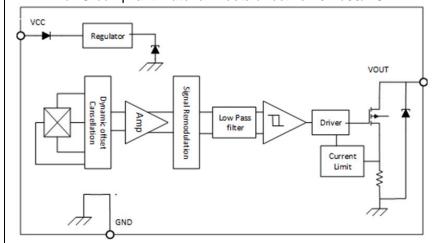
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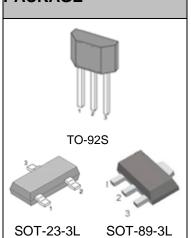
Preliminary Datasheet 1.3

FEATURES and FUNCTIONAL DIAGRAM

- AEC-Q100 automotive qualified for CHA93X
- Digital Omnipolar-Switch Hall Sensor
- Superior Temperature Stability
- Multiple Sensitivity Options (BOP / BRP):
 ±25 / ±15 Gauss: ±70 /±35 Gauss: ±100/ ±50 Gauss:
- On board voltage regulator for 2.5V to 22V range
- Open Drain Output (25 mA Sink)
- Resistant to physical stress
- Output short-circuit protection
- Operation from unregulated supply
- Reverse-battery and freewheeling protection
- Solid-state reliability
- Wide Operating temperature range: -40 to 150 °C
- Small package sizes TO-92S, SOT-23 and SOT-89
- RoHS-compliant material meets directive 2011/65/EU



PACKAGE



APPLICATIONS

-Docking Detection
-Door Open and Close
Detection
-Proximity Sensing
-Valve Positioning
-Pulse Counting
-Flow rate sensing
-Robotic control (cylinder position monitoring)
-Float-based fluid level sensing
-Speed and RPM sensing in

fitness equipment

DESCRIPTION

The CHA93X/CHI93X Hall-effect sensor is extremely temperature-stable and stress-resistant sensor ICs, especially suited for operation over extended temperature ranges from -40°C to 150°C. Superior high temperature performance is possible through dynamic offset cancellation, which reduces the residual offset voltage normally caused by device over-molding, temperature dependencies, and thermal stress.

The device includes a voltage regulator, Hall-voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, and a short circuit protected open-drain output to sink up to 25 mA.

An on-board regulator permits operation with supply voltages of 2.5 to 22 V. The advantage of operating down to 2.5V is that the device can used in 2.5V applications or with additional external resistance in series with the supply pin for greater protection against high-voltage transient events.

The CHA93X/CHI93X series is digital Omnipolar Hall switch. When the applied magnetic flux density exceeds the BOP threshold, the chip open-drain output goes low. The output stays low until the field decreases to less than BRP, and then the output goes to high impedance.

The CHA93X/CHI93X also integrated internal clamps against supply/output transients; output short circuits protection; reverse battery conditions.

Three package styles provide a magnetically optimized package for most applications, SOT-23, TO-92S and SOT-89. Each package type is lead (Pb) free (suffix, –T), with a 100% matte-tin-plated lead-frame.

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1. Product Family Members

Part Number	Marking ID	Description
CHA931SR	C931	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-23-3L package, tape and reel packing (3000 units per reel)
CHA931TB	C931	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, bulk packing (1000 units per bag)
CHA931ER	C931	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-89-3L package, tape and reel packing (1000 units per reel)
CHA932SR	C932	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-23-3L package, tape and reel packing (3000 units per reel)
СНА932ТВ	C932	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, bulk packing (1000 units per bag)
CHA932ER	C932	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-89-3L package, tape and reel packing (1000 units per reel)
CHA933SR	C933	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-23-3L package, tape and reel packing (3000 units per reel)
СНА933ТВ	C933	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, bulk packing (1000 units per bag)
CHA933ER	C933	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-89-3L package, tape and reel packing (1000 units per reel)
CHI931SR	I931	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-23-3L package, tape and reel packing (3000 units per reel)
CHI931TB	1931	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, bulk packing (1000 units per bag)
CHI931TR	I931	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, tape and reel packing (3000 units per reel)
CHI931ER	1931	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-89-3L package, tape and reel packing (1000 units per reel)
CHI932SR	1932	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-23-3L package, tape and reel packing (3000 units per reel)
CHI932TB	1932	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, bulk packing (1000 units per bag)
CHI932ER	1932	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-89-3L package, tape and reel packing (1000 units per reel)
CHI933SR	1933	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-23-3L package, tape and reel packing (3000 units per reel)
СНІ933ТВ	1933	Omnipolar-Switch, Hall-effect digital sensor IC, flat, TO-92S package, bulk packing (1000 units per bag)
CHI933ER	1933	Omnipolar-Switch, Hall-effect digital sensor IC, SOT-89-3L package, tape and reel packing (1000 units per reel)



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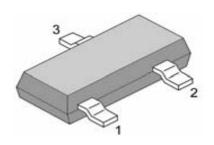
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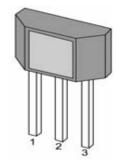
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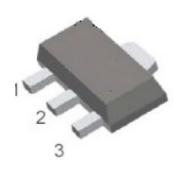
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2. Pin Definitions and Descriptions

SOT-23-3L (S)	TO-92S (T)	SOT-89-3L (E)	Name	Type	Function
1	1	1	VDD	Supply	Supply Voltage pin
2	3	3	OUT	Output	Open Collector Output pin
3	2	2	GND	Ground	Ground pin







SOT-23-3L

TO-92S

SOT-89-3L

3. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Units
Supply Voltage	V_{DD}	-	24	V
VDD Reverse Voltage VDD	V_{RDD}	-22		V
Supply Current	I_{DD}	-	20	mA
Output Voltage	V_{OUT}	-0.3	24	V
Output Current	I _{OUT}	-	25	mA
Operating Ambient Temperature	T _A	-40	150	°C
Storage Temperature	Ts	-50	150	°C
Junction temperature	TJ	-50	165	°C
Magnetic Flux	В	No Limit G		Gauss

Note: Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute-maximum- rated conditions for extended periods may affect device reliability.

4. ESD Protections

202 : 10:00:0:0				
Parameter	Value	Unit		
All pins 1)	+/-8000	V		
All pins 2)	+/-200	V		
All pins 3)	+/-750	V		

- 1) HBM (Human Body Mode) according to AEC-Q100-002
- 2) MM (Machine Mode) according to AEC-Q100-003
- 3) CDM (charged device mode) according to AEC-Q100-011



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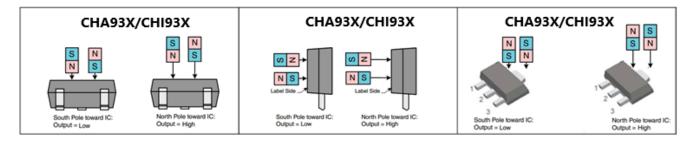
5. Function Description

The CHA93X/CHI93X exhibits digital Omnipolar switching characteristics. Therefore, it requires only south poles or north poles to operate properly.

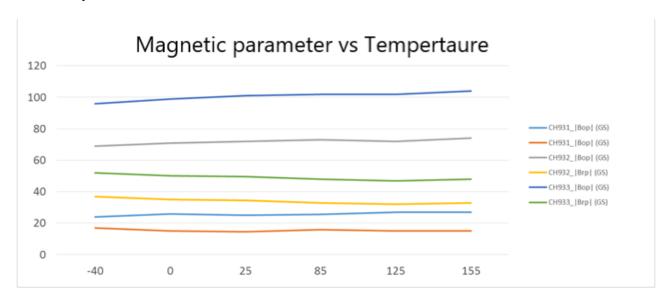
When the applied magnetic flux density exceeds the BOP threshold, the chip open-drain output goes low. The output stays low until the field decreases to less than BRP, and then the output goes to high impedance.

A magnetic hysteresis BHYST keeps BOP and BRP separated by a minimal value. This hysteresis prevents output oscillation near the switching point.

6. Magnetic Activation



7. Temperature Characteristics





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8. Parameters Specification (VCC=3.3V supply, TA= -40 $^{\circ}$ C to 150 $^{\circ}$ C except where otherwise specified.)

therwise specified.)	Tool Condition	D./Line	T	Marrie	Holton
			Typ.		Units
		2.5	-	22	V
	$V_{DD} = 3.3V$	-	1.6	3	mA
Voltage	I _{CC} =7 mA; TA = 25°C	24			V
Output Zener Clamp Voltage	$I_{OUT} = 3mA$	24			V
Reverse Battery Zener				-22	V
Reverse Battery Current	$V_{CC} = -22 \text{ V}$	-5			mA
Chopping Frequency			500		KHz
Power-On Time	$TA = 25$ °C; $C_{LOAD} = 10$ pF	-	_	30	μs
Output saturation voltage	at 20mA, Gauss >BOP	-	-	0.4	V
Output Leakage Current	VOUT = 24 V; Switch state = Off	-	-	10	uA
Output Current Limit	Short-Circuit Protection	30	_	90	mA
Output rise time	R_{LOAD} = 820 Ω , C_{LOAD} = 10 pF;	-	0.2	2	uS
-	R_{LOAD} = 820 Ω , C_{LOAD} = 10 pF;	-	0.1	2	uS
	B=Brp-100G to Bop+100G in 1us		13	25	μs
Thermal resistance: SOT-23-3L TO-92S SOT-89-3L	-	- - -	303 203 230	- - -	°C /W °C/W
Maximum Switching Frequency		20	30		KHz
Operating temperature	-	-40	-	150	°C
Storage temperature:	-	-40	-	150	°C
CHI931					
Magnetic operating point	T _A =-40°C to 150°C	±15	±30	±55	Gauss
Magnetic release point	T _A =-40°C to 150°C	±5	±20	±45	Gauss
Magnetic hysteresis window BOP - BRP	T _A =-40°C to 150°C	4	10	30	Gauss
Magnetic offset; $B_0 = (BOP + BRP) / 2$	T _A =-40°C to 150°C		20		Gauss
CHA932/CHI932					
Magnetic operating point	T _A =-40°C to 150°C	±30	±60	±90	Gauss
Magnetic release point	T _A =-40°C to 150°C	±15	±30	±60	Gauss
Magnetic hysteresis window BOP - BRP	T _A =-40°C to 150°C	20	30	50	Gauss
Magnetic offset; $B_0 = (BOP + BRP) / 2$	T _A =-40°C to 150°C		45		Gauss
CHI933					
Magnetic operating point	T _A =-40°C to 150°C	±70	±100	±150	Gauss
	Supply voltage Supply Current Supply Zener Clamp Voltage Output Zener Clamp Voltage Reverse Battery Zener Reverse Battery Current Chopping Frequency Power-On Time Output saturation voltage Output Leakage Current Output Current Limit Output rise time Output fall time Output delay Time Thermal resistance: SOT-23-3L TO-92S SOT-89-3L Maximum Switching Frequency Operating temperature Storage temperature: CHI931 Magnetic operating point Magnetic release point Magnetic hysteresis window BOP - BRP Magnetic operating point Magnetic release point Magnetic release point Magnetic release point Magnetic release point Magnetic operating point Magnetic operating point Magnetic release point Magnetic offset; Bo = (BOP + BRP) / 2 CHI932 CHI933	Parameter Test Condition Supply voltage -40 °C to 150 °C Supply Current V _{DD} = 3.3V Supply Zener Clamp Voltage I _{CC} =7 mA; TA = 25°C Output Zener Clamp Voltage I _{OUT} = 3mA Reverse Battery Zener Reverse Battery Current Chopping Frequency V _{CC} = -22 V Power-On Time TA = 25°C; C _{LOAD} = 10 pF Output saturation voltage at 20mA, Gauss >BOP Output Leakage Current VOUT = 24 V; Switch state = Off Output Current Limit Short-Circuit Protection Output rise time R _{LOAD} = 820 Ω, C _{LOAD} = 10 pF; Output fall time R _{LOAD} = 820 Ω, C _{LOAD} = 10 pF; Output delay Time B=Brp-100G to Bop+100G in 1us Thermal resistance: SOT-23-3L TO-92S SOT-89-3L Maximum Switching Frequency - Operating temperature - Storage temperature: - CHI931 T _A =-40°C to 150°C Magnetic operating point T _A =-40°C to 150°C Magnetic offset; Bo = (BOP + BRP) / 2 T _A =-40°C to 150°C	Parameter	Parameter	Parameter



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B _{RP}	Magnetic release point	T _A =-40°C to 150°C	±30	±50	±100	Gauss
Внуѕт	Magnetic hysteresis window BOP - BRP	T _A =-40°C to 150°C		50		Gauss
Bo	Magnetic offset; B ₀ = (BOP + BRP) / 2	T _A =-40°C to 150°C		75		Gauss

^{(1) 1} mT = 10 Gauss

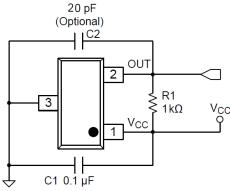
NOTICE

The magnetic field strength (Gauss) required to cause the switch to change state (operate and release) will be as specified in the magnetic characteristics. To test the switch against the specified magnetic characteristics, the switch must be placed in a uniform magnetic field.

9. Application Information

9.1 Typical Application

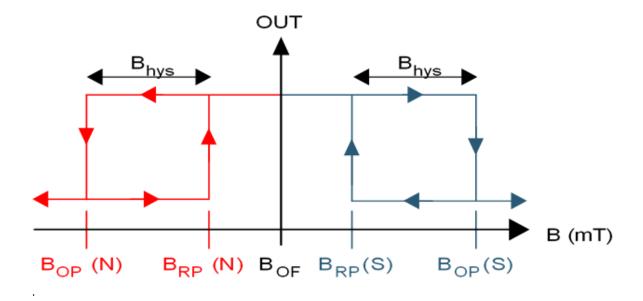
It is recommended that an external capacitor C1 is connected to the supply. This can reduce the noise injected into the device. Normal 0.1uF is suggested.



Typical Application Circuit

9.2 Device Output

If the device is powered on with a magnetic field strength between BRP and BOP, then the device output is indeterminate and can either be Hi-Z or Low. If the field strength is greater than BOP, then the output is pulled low. If the field strength is less than BRP, then the output is released.



⁽²⁾ Bandwidth describes the fastest changing magnetic field that can be detected and translated to the output.



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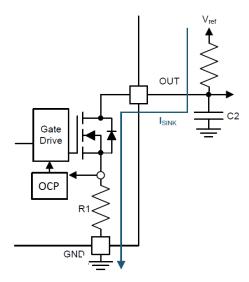
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9.3 Output Stage

The CHA93X/CHI93X output stage uses an open-drain NMOS, and it is rated to sink up to 30 mA of current. For proper operation, calculate the value of the pullup resistor R1 using Equation 1.

$$\frac{V_{ref} max}{30 mA} \le R1 \le \frac{V_{ref} min}{100 \mu A} \tag{1}$$

The size of R1 is a tradeoff between the OUT rise time and the current when OUT is pulled low. A lower current is generally better, however faster transitions and bandwidth require a smaller resistor for faster switching. In addition, ensure that the value of R1 > 500 Ω to ensure the output driver can pull the OUT pin close to GND.



Select a value for C2 based on the system bandwidth specifications as shown in Equation 2.

$$2 \times f_{\text{BW}} \text{ (Hz)} < \frac{1}{2\pi \times \text{R1} \times \text{C2}}$$
 (2)

Most applications do not require this C2 filtering capacitor.

9.4 Protection Circuits

The CHA93X/CHI93X device is fully protected against overcurrent and reverse-supply conditions.

9.5 Overcurrent Protection (OCP)

An analog current-limit circuit limits the current through the FET. The driver current is clamped to IOCP. During this clamping, the rDS(on) of the output FET is increased from the nominal value.

9.6 Reverse Supply Protection

The CHA93X/CHI93X device is protected in the event that the VCC pin and the GND pin are reversed (up to -22 V).



CHA93X/CHI93X

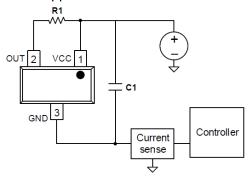
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9.7 Alternative Two-Wire Application

For systems that require minimal wire count, the device output can be connected to VCC through a resistor, and the total supplied current can be sensed near the controller.



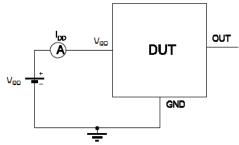
2-Wire Application

Current can be sensed using a shunt resistor or other circuitry.

10. Test Conditions

Note: DUT=Device Under Test

Supply Current

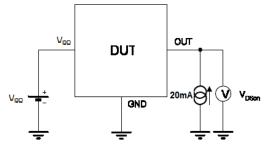


Note 1 - The supply current lop represents the static supply current.

OUT is left open during measurement

Note 2 - The device is put under magnetic field with B<BRP

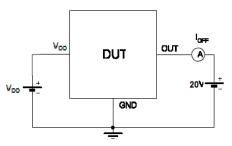
Output Saturation Voltage



Note 1 - The output saturation voltage VDSon is measured at VDD=3.3 V and VDD=20V

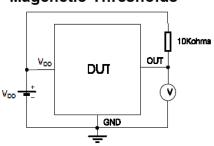
Note 2 - The device is put under magnetic field with B>Bop

Output Leakage Current



Note 1 - The device is put under magnetci field with B<BRP

Magenetic Thresholds



Note 1 - Bop is determined by putting the device under magnetic field swept from BRPmin up to Bopmax until the output is switched on.

Note 2 - BRP is determined by putting the device under magnetic field swept from Bopmax down to BRPmin until the output is switched off.



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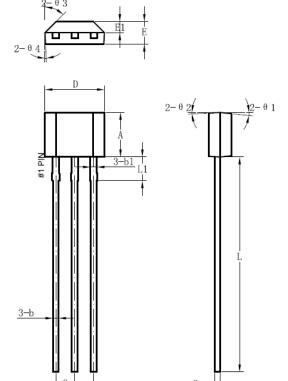
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11. Package and Packing Information: For CHA93XTB and CHI93XTB:





Symbol	Dimensions in Millimeters					
Symbol	Min.	Тур.	Max.			
Α	2.9	3	3.1			
b	0.35	0.39	0.56			
b1		0.44				
С	0.36	0.38	0.51			
D	3.9	4	4.1			
E	1.42	1.52	1.62			
E1		0.75				
е		1.27				
e1		2.54				
L	13.5	14.5	15.5			
L1		1.6				
θ1		6°				
θ2		3°				
θ3		45°				
θ4		3°				



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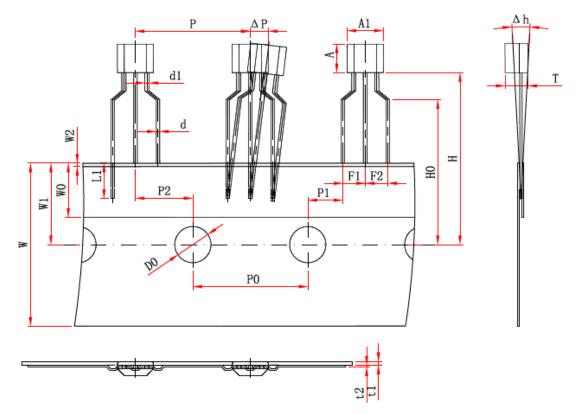
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For CHI931TR only:

TO-92S PACKAGE TAPEING DIMENSION



Item	Symbol	Value & Tolerance
Body width	A1	4.0 ± 0.1
Body height	Α	3.15 ± 0.1
Body thickness	Т	1.52 ± 0.1
Lead wire diameter	d	0.38+0.1, - 0.05
Lead wire diameter1	d1	0.46+ 0.05, - 0.06
Pitch of component	Р	12.7 ± 0.3
Feed hole pitch	P0	12.7 ± 0.2
Hole center to component center	P2	6.35 ± 0.3
Lead to lead distance	F1,F2	2.5 ± 0.3
Component alignment, F-R	△h	0 ± 1.0
Type width	W	18.0 + 1.0, - 0.5
Hole down tape width	W0	6.0 ± 0.5
Hole position	W1	9.0 ± 0.5
Hole down tape position	W2	1.0MAX.
Height of component from tape center	Н	19.0 +2.0, -1.0
Lead wire clinch height	H0	16.0 ± 0.5
Lead wire(tape portion)	L1	2.50 MIN.
Feed hole diameter	D0	4.0 ± 0.2
Carrier Tape Thickness	t1	0.4 ± 0.05
Taped Lead Thickness	t2	0.2 ± 0.05
Position of hole	P1	3.85±0.3
Component alignment	△P	0 ± 1.0
		Unit : mm



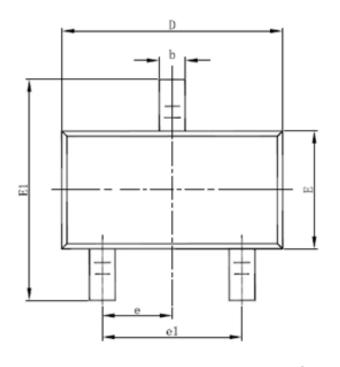
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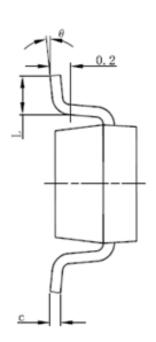
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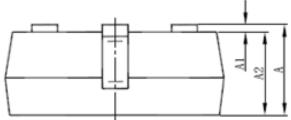
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PACKAGE DESIGNATOR SOT-23-3L







Cb.a.l	Dimensions In	Millimeters	Dimensions	In Inches
Symbol	Min	Max	Min	Max
Α	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950(BSC)		0.037(BSC)
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°



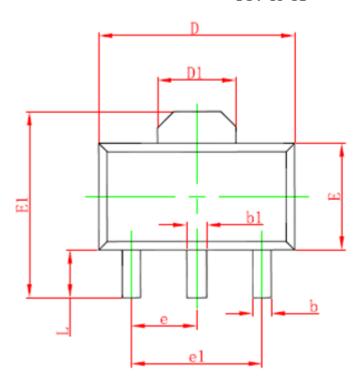
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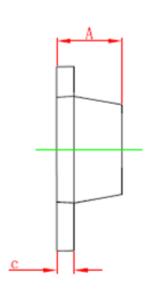
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PACKAGE DESIGNATOR SOT-89-3L





Symbol	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
С	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550	REF.	0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
е	1.500 TYP.		0.060	TYP.
e1	3.000 TYP.		0.118	TYP.
L	0.900	1.200	0.035	0.047



CHA93X/CHI93X

Automotive Product Group

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Preliminary Datasheet 1.3

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